

#### WEBINAR

# Industrial applications of micro-XRF – Quality control at different stages

Bruker Nano Analytics - Micro-XRF applications

#### The speakers





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- Application Scientist, Bruker Nano Analytics, Berlin, Germany

### Agenda

Introduction

Micro-XRF in general

Incoming goods inspection – Qualitative analysis

4

Incoming goods inspection – Quantitative analysis Process control

Quality control – Qualitative analysis

Quality control – Quantitative analysis

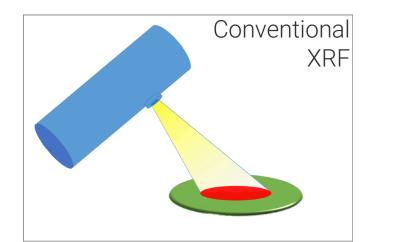
Summary and Q&A session



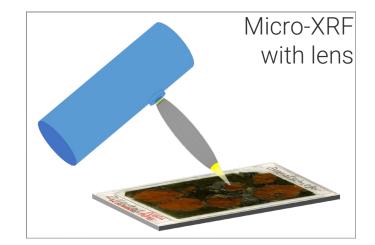


#### From XRF to micro-XRF











Composition



#### Compositional variations



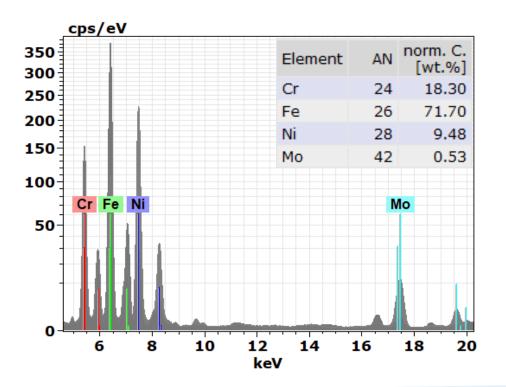


# From XRF to micro-XRF

- **Conventional X-ray fluorescence analysis** (XRF) is an analytical tool for qualitative and quantitative material analysis. It performs ideally in a **standardized workflow**.
- XRF tells you which elements are in the sample and how much of each one.
- Usually a sample needs "preparation", including homogenization and/or dilution for matrix reduction.

Information is lost!

The compositional variations in a sample may be a crucial property of the material!



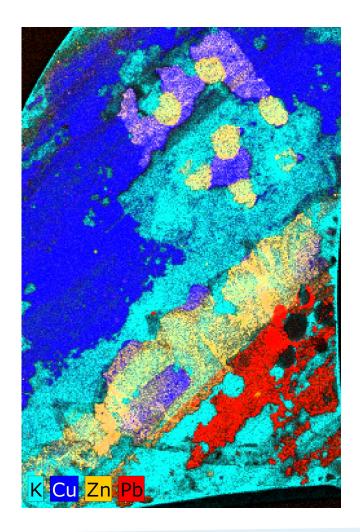


#### **Micro-XRF**

Micro-XRF is XRF with a small spot (nowadays typically < 20 μm).</li>

- $\rightarrow$  Micro-XRF reveals where elements are.
- $\rightarrow$  Micro-XRF is ideal for non-homogeneous samples.
- It usually requires minimal or no sample preparation.
- Quantitative micro-XRF is feasible for sufficiently homogeneous areas of the sample, which can be even below 100 µm in diameter.
- The measurement conditions are very flexible in order to address different analytical tasks or requirements posed by the sample.

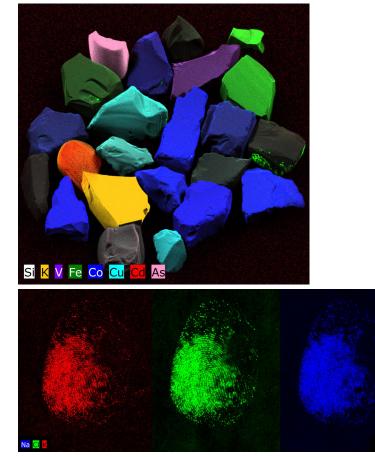






### Micro-XRF What is it used for?

#### Forensics and life sciences





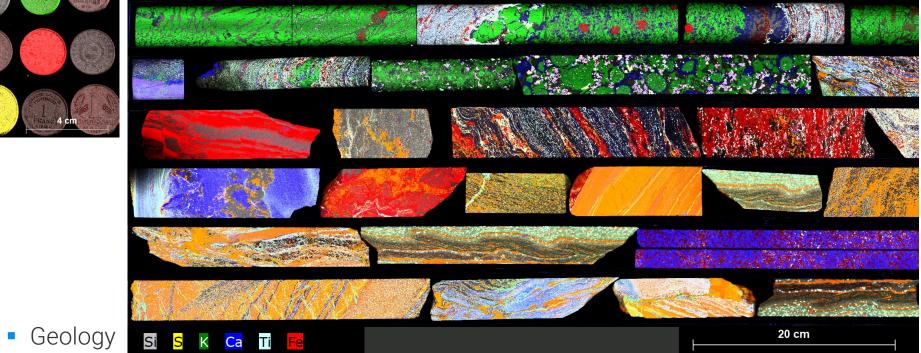


### Micro-XRF What is it used for?





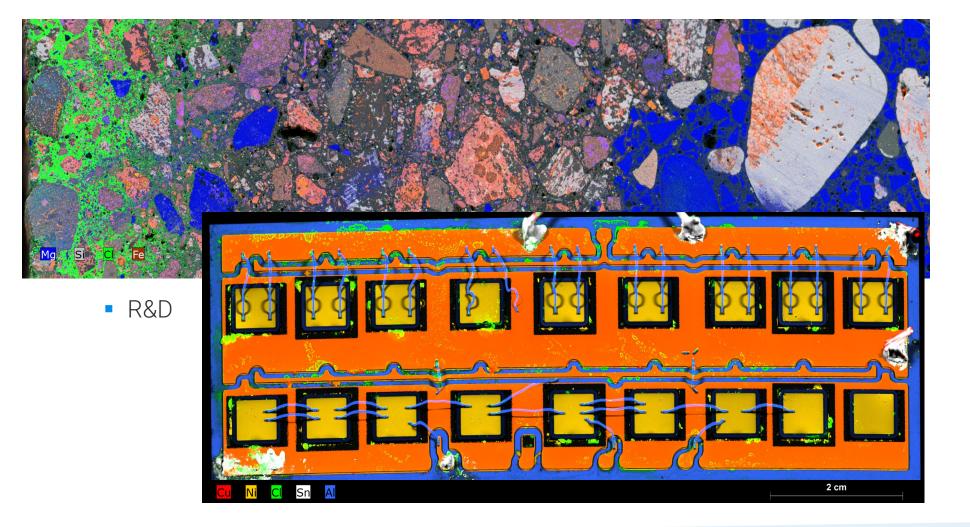
• Art, conservation, archaeology



### Micro-XRF What is it used for?

BRUKER

Materials science



#### Micro-XRF Uses in industrial environment



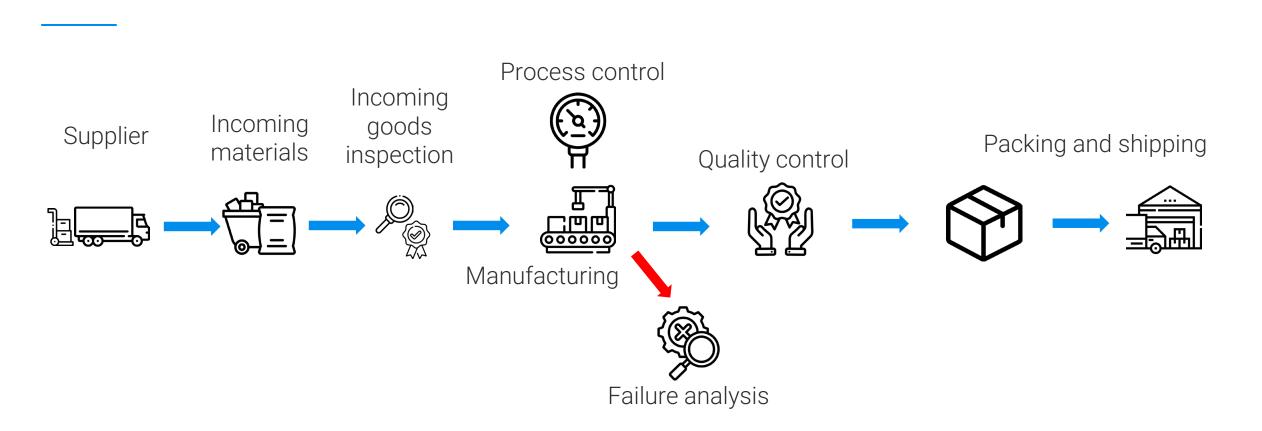
- Micro-XRF is well established in academic environment and the R&D or central labs of large companies.
- ... but where does it fit in a more industrial environment?

- Even though it is possible to operate the M4 TORNADO in an automated environment, this will not be the topic of this presentation.
- We will discuss the standard operation of the instrument and where its analytical methods are beneficial in an industrial workflow.



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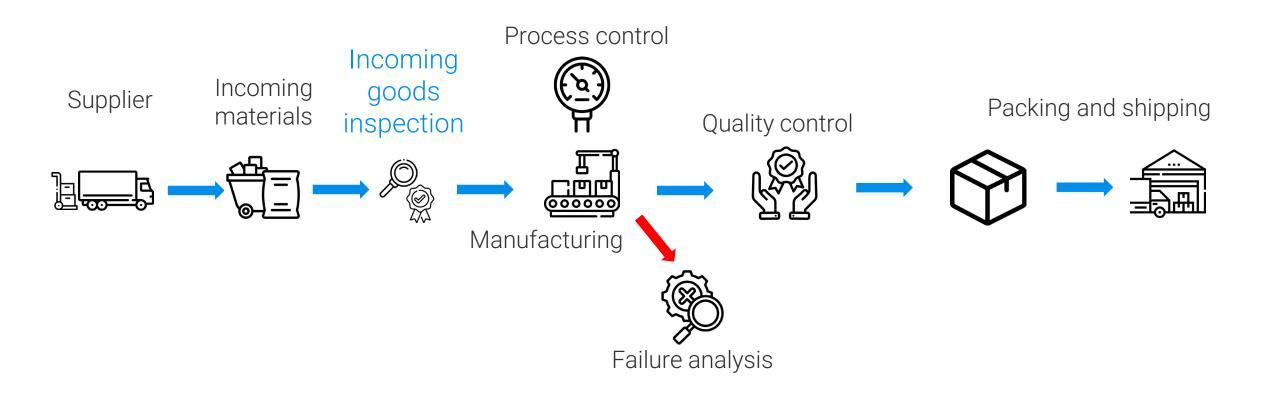
### Micro-XRF – Quality control at different stages





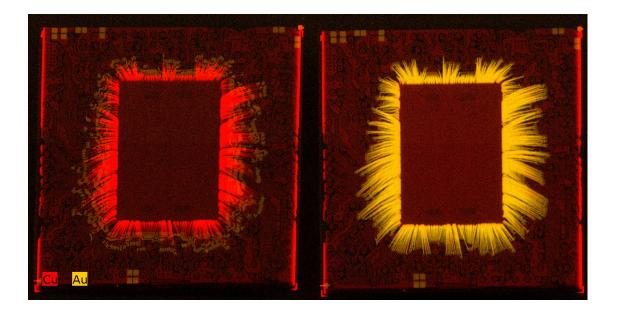
### Micro-XRF – Quality control at different stages Incoming goods inspection



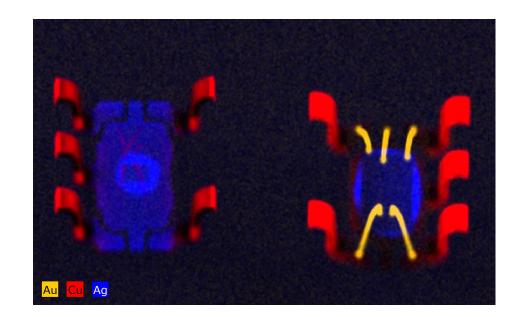


### Incoming goods inspection Qualitative analysis

- Updated chip design, announced by the manufacturer:
  - Copper wires instead of gold to save costs.



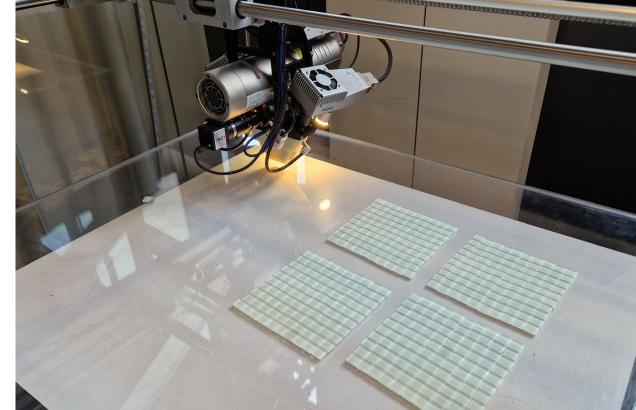
- Here a new supplier sent a batch of ICs with the same designation who behaved differently when tested.
- Micro-XRF showed a different inner design.





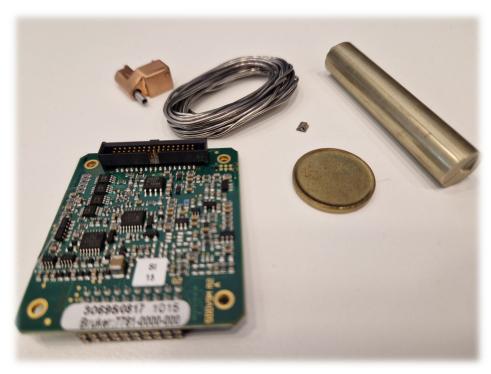
#### Incoming goods inspection Qualitative analysis

- With sufficiently clear criteria (Au wires in ICs) even qualitative analysis can be done as point measurements, maybe with collimator.
- Example here: in batches of glass tiles, a specific subset of potassium-rich tiles needs to be identified.





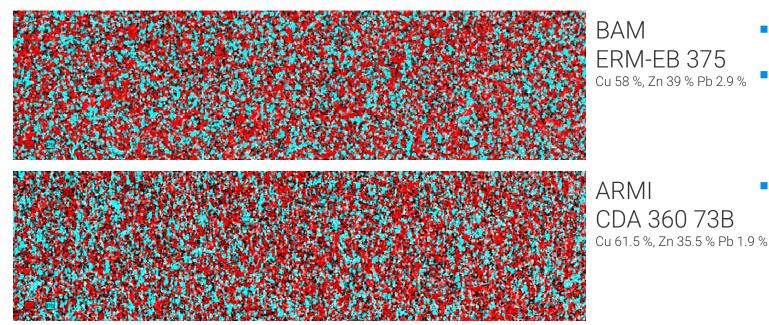
### Incoming goods inspection Quantitative analysis – Introduction



Some challenging samples

- When using metal alloys as raw materials a quantitative analysis of incoming goods is vital.
- Next to OES, XRF is the most common method for incoming goods inspection, be it handheld, benchtop or floor-standing.
- When the samples are too small for larger instruments, micro-XRF can be used with high results quality.
- Also, it has the benefit of being relatively forgiving when it comes to adverse sample shapes.
  - However, like for most techniques, a more sophisticated sample preparation (flat surfaces) and thorough sample placement (horizontal alignment) greatly improves the attainable quality of the results.

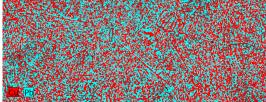
#### Incoming goods inspection Quantitative analysis – Copper alloys



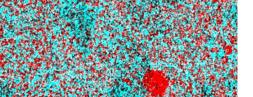


- Element distribution in bronzes
- The alloy is clearly inhomogeneous, because the lead (added as cutting aid) forms inclusions.
- Quantification is possible with
  - Collimator measurements,
  - the sum spectrum of a map,
  - the average values of a sufficiently large set of point measurements.

LGC Standards SUS RC36 Cu 82.5 %, Zn 0.25 % Pb 9.6 %



ARMI CDA 932 Cu 83.2 %, Zn 2.6 % Pb 6.8 %

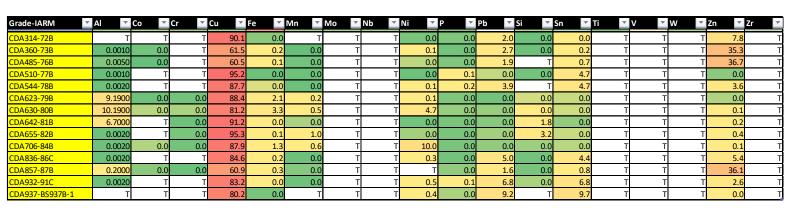


ARMI CDA 397 Cu 80.2 %, Zn 0.0

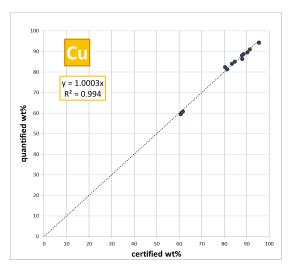
# Cu 80.2 %, Zn 0.04 % Pb 9.2 %

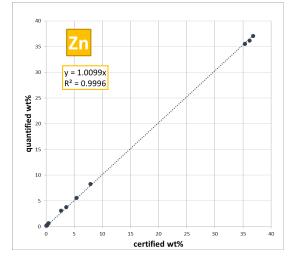
Innovation with Integrity | 16

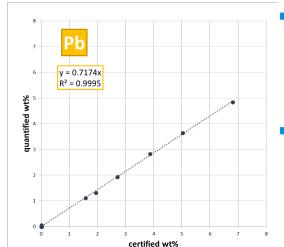
### Incoming goods inspection Quantitative analysis – Copper alloys



- (Type-)calibration of the M4 TORNADO's FP quantification needs reference materials.
- Measure sets of samples of known composition and quantify them.





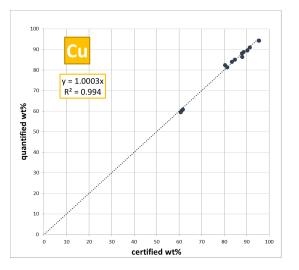


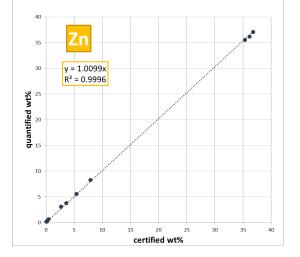
- The initial correlation already is usually very linear.
- The slopes of the correlation may need to be adapted (=calibrated).

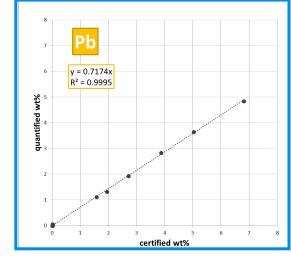


#### Incoming goods inspection Quantitative analysis – Copper alloys

Grade-IARM	Al	Co	Cr	Cu	Fe	Mn	Mo 🔽 Nb	Ni	P	Pb	Si	Sn 💌	Ti	V	W	Zn	Zr 💌
CDA314-72B	Т	Т	T	90.1	0.0	Т	Т	0.0	0.0	2.0	0.0	0.0	Т	Т	Т	7.8	Т
CDA360-73B	0.0010	0.0	) T	61.5	0.2	0.0	T I	0.1	0.0	2.7	0.0	0.2	Т	Т	Т	35.3	Т
CDA485-76B	0.0050	0.0	) T	60.5	0.1	0.0	Т	0.0	0.0	1.9	Т	0.7	Т	T	Т	36.7	Т
CDA510-77B	0.0010	Т	T	95.2	0.0	0.0	Т	0.0	0.1	0.0	0.0	4.7	Т	T	Т	0.0	Т
CDA544-78B	0.0020	T	T	87.7	0.0	0.0	Т	0.1	0.2	3.9	Т	4.7	Т	Т	Т	3.6	Т
CDA623-79B	9.1900	0.0	0.0	88.4	2.1	0.2	T T	0.1	0.0	0.0	0.0	0.0	Т	Т	Т	0.0	Т
CDA630-80B	10.1900	0.0	0.0	81.2	3.3	0.5	T T	4.7	0.0	0.0	0.0	0.0	Т	Т	Т	0.1	Т
CDA642-81B	6.7000	Т	0.0	91.2	0.0	0.0	Т	0.0	0.0	0.0	1.8	0.0	Т	T	Т	0.2	Т
CDA655-82B	0.0020	Т	0.0	95.3	0.1	1.0	Т	0.0	0.0	0.0	3.2	0.0	Т	Т	Т	0.4	Т
CDA706-84B	0.0020	0.0	0.0	87.9	1.3	0.6	Т	10.0	0.0	0.0	0.0	0.0	Т	Т	Т	0.1	Т
CDA836-86C	0.0020	Т	T	84.6	0.2	0.0	Т	0.3	0.0	5.0	0.0	4.4	Т	Т	Т	5.4	Т
CDA857-87B	0.2000	0.0	0.0	60.9	0.3	0.0	Т	T	0.0	1.6	0.0	0.8	Т	Т	Т	36.1	Т
CDA932-91C	0.0020	T	T	83.2	0.0	0.0	Т	0.5	0.1	6.8	0.0	6.8	Т	Т	Т	2.6	Т
CDA937-BS937B-1	Т	Т	Т	80.2	0.0	Т	Т	0.4	0.0	9.2	Т	9.7	Т	Т	Т	0.0	Т







#### **CONFIGURATION - SPECTRUM ELEMENTS** Elements Use spectrum elements н ✓ Use list elements Li Be Ne Search additional elements 0 Na Mg CL Ar K Ca Sc Ti V Cr Mn Fe Co Ni Cu Zn Ga Ge Br Kr Rb Sr Y Zr Nb Mo Tc Ru Rh Pd Ag Cd In Sn Sb Te I Xe Cs Ba La Hf Ta W Re Os Ir Pt Au Hg TI Fr Ra Ac Ce Pr Nd Pm Sm Eu Gd Tb Dy Ho Er Tm Yb Lu Th Pa U Np Pu Am Cm Bk Cf Es Fm Md No Lr Clear all Double click an element to open element editor

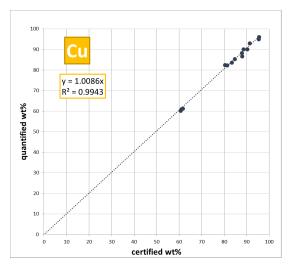
#### Special properties of selected elements

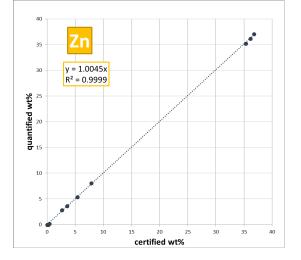
#### Fact. Compound 1.00 Stoichiom. elements Cu 0.92 Fix concentration Zn 0.91 Deconvolution only Rh V . 1.00 Excluded element Pb 1.37 Difference element **Global options** Background cycles Minimum concentration Default 0.00 % Manual 120 V NNLS Description Load... Cancel Save... OK

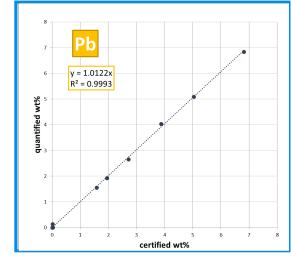


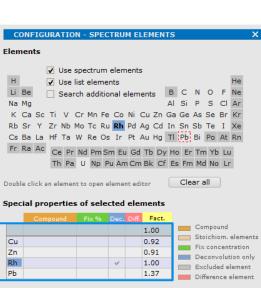
#### Incoming goods inspection Quantitative analysis – Copper alloys

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CDA510-77B	0.0010	Т	T	95.2	0.0	0.0	Т	Т	0.0	0.1	0.0	0.0	4.7	Т	Т	Т	0.0	Т
CDA544-78B	0.0020	Т	T	87.7	0.0	0.0	Т	Т	0.1	0.2	3.9	Т	4.7	Т	Т	Т	3.6	Т
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CDA655-82B	0.0020	Т	0.0	95.3	0.1	1.0	Т	Т	0.0	0.0	0.0	3.2	0.0	Т	Т	Т	0.4	Т
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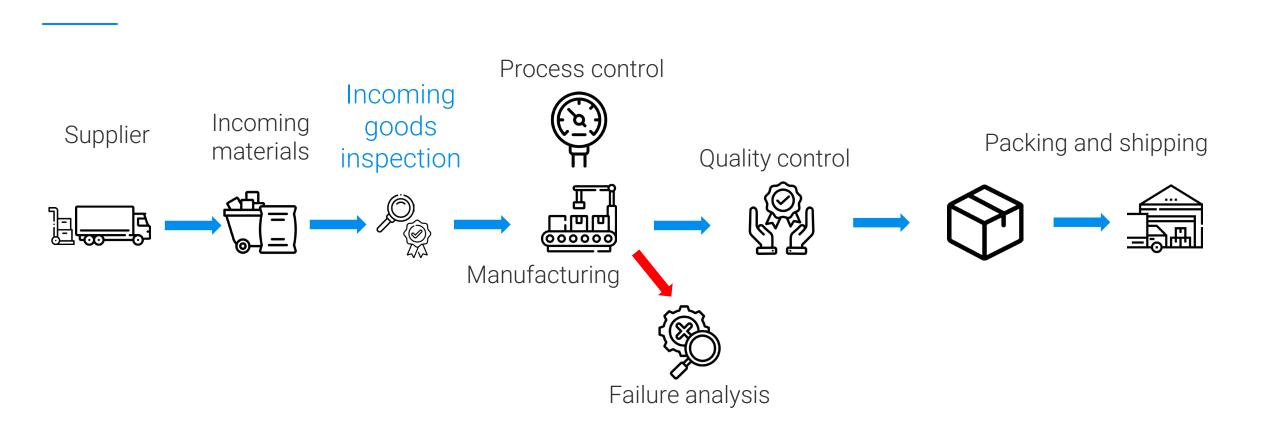


#### Global options

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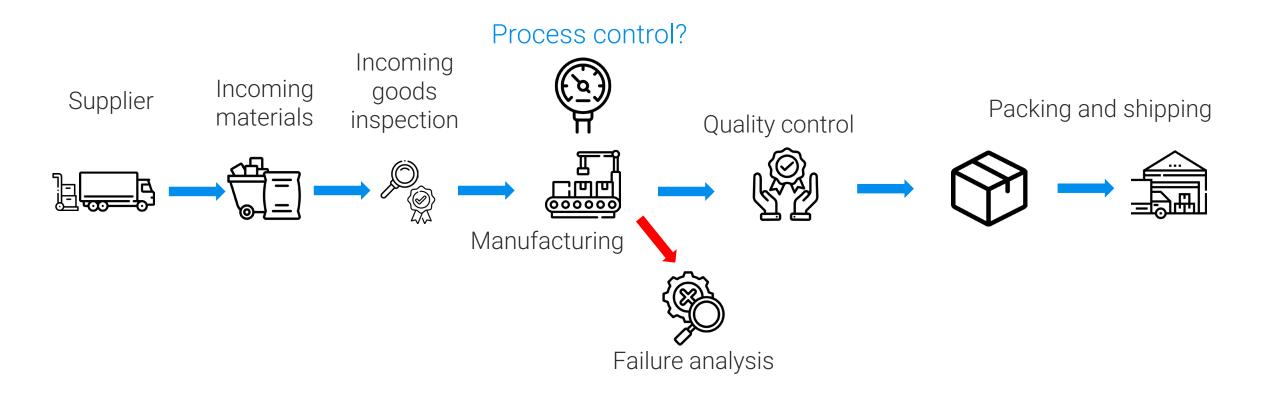


### Micro-XRF – Quality control at different stages



#### Micro-XRF – Quality control at different stages Process control





### **Process control** Is it feasible?

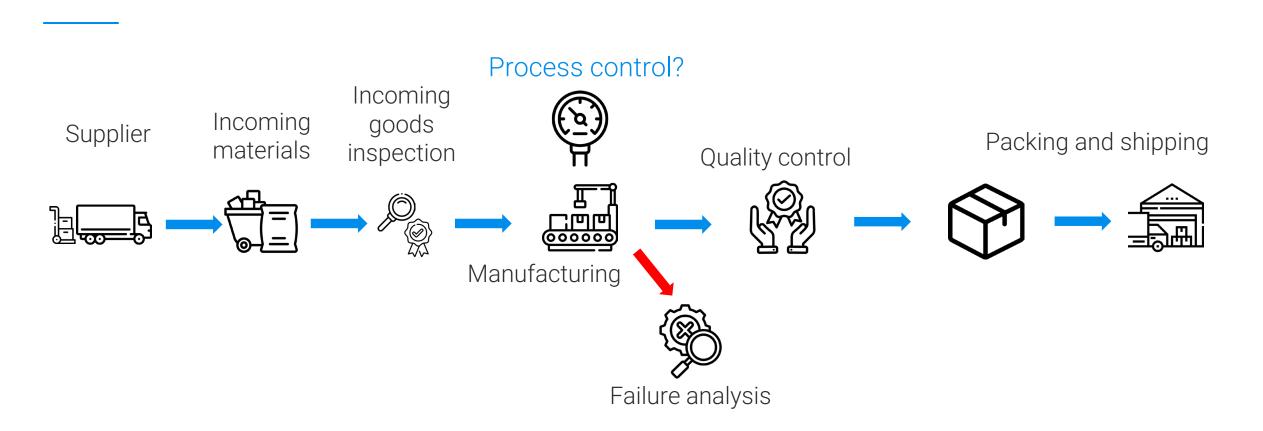
- True on-line analysis with XRF is possible but with micro-XRF it is ... challenging.
- (semi-)automated point measurements with open-beam instruments are the immediate application.





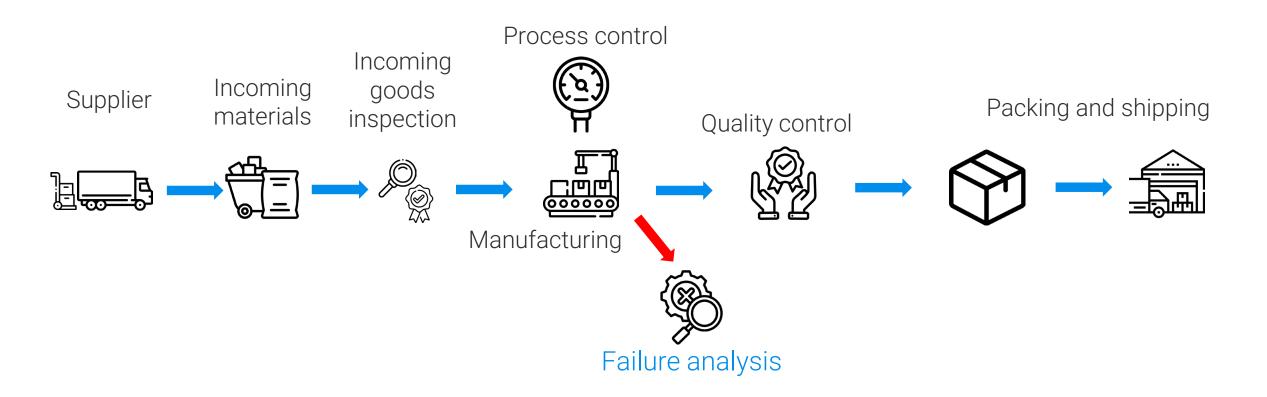


### Micro-XRF – Quality control at different stages



### Micro-XRF – Quality control at different stages Failure analysis





### Failure analysis Example – Stripped threads in aluminium



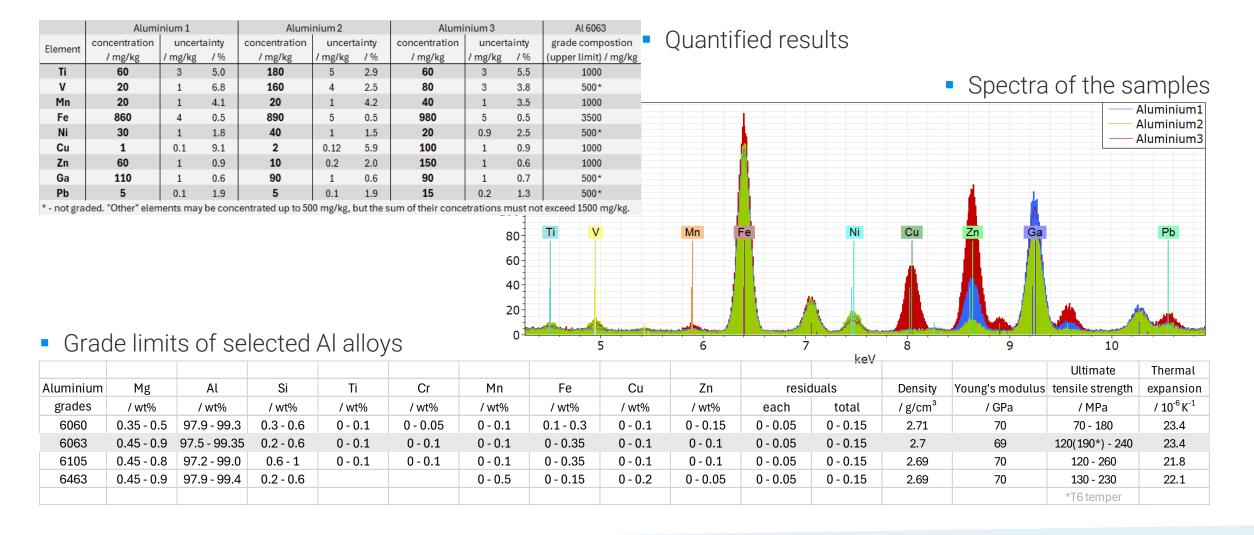
- AI 6063 is a commonly used aluminium alloy, well suited for aluminium extrusion with smooth surfaces that allow for anodizing.
- In one batch of products, it was not possible to insert the screws as usual because the threads could not withstand the mechanical stresses.
- In aluminium, even more than in other alloys, the mechanical properties are not only a matter of composition but above all of microstructure, which can be finely tuned by heat treatment (temper).



 Sometimes even the crystalline structure can be resolved by micro-XRF.

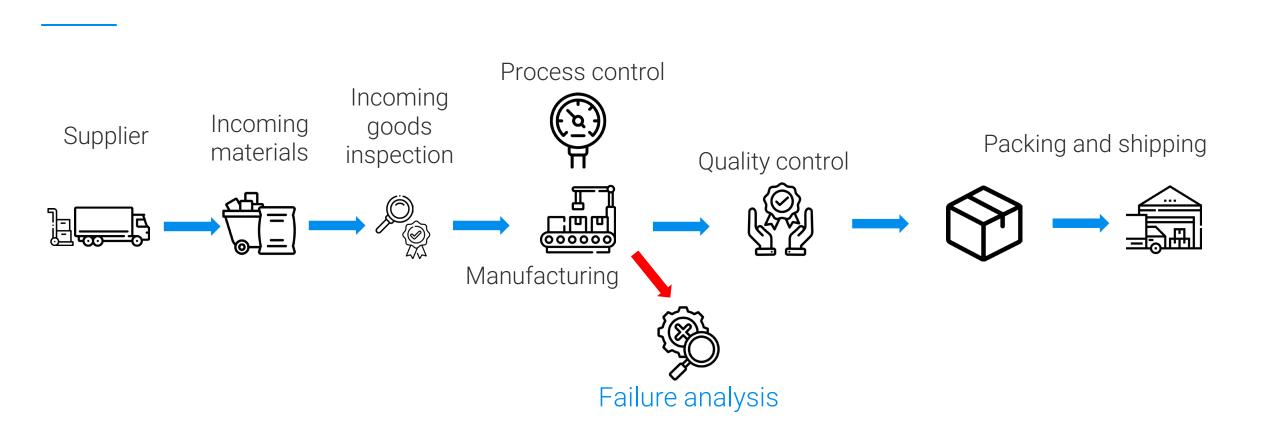


### Failure analysis Alloy element quantification



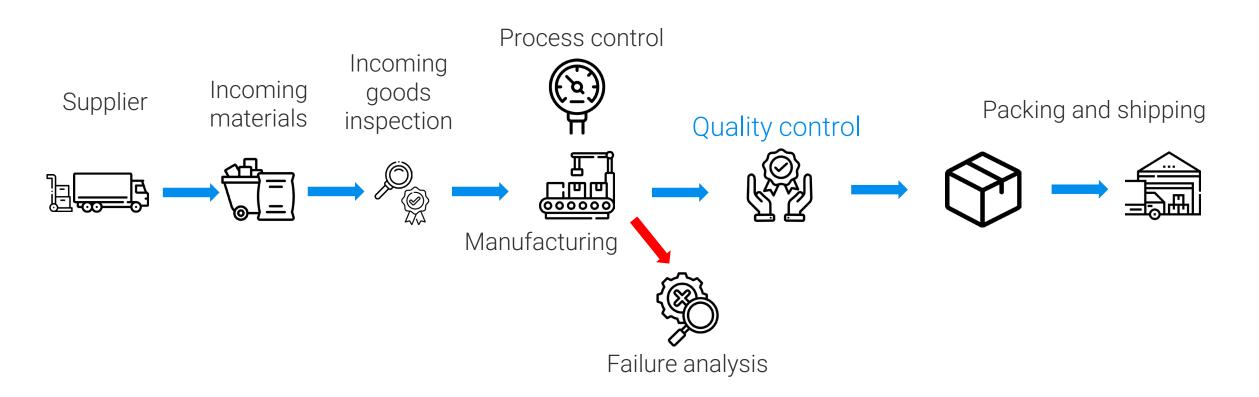


### Micro-XRF – Quality control at different stages



### Micro-XRF – Quality control at different stages Quality control



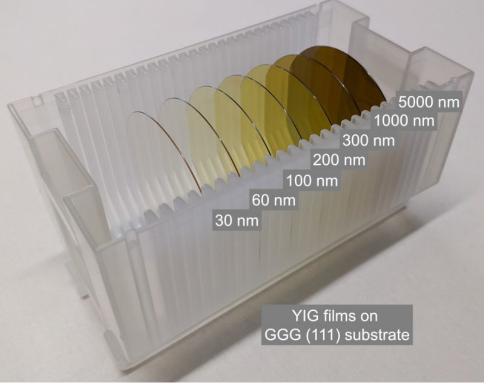


#### Quality control YIG layer analysis

- Due to outstanding magnetic properties, Yttrium iron garnet (YIG) thin films grown on a lattice matched substrate (GGG, gadolinium gallium garnet) are increasingly being produced commercially.
- Important properties like magnetic damping factor scale with the thickness of the thin film.

 $\rightarrow$  Thickness needs to be quantified to gauge the material performance.

 $\rightarrow$  Micro-XRF may be used for this purpose.

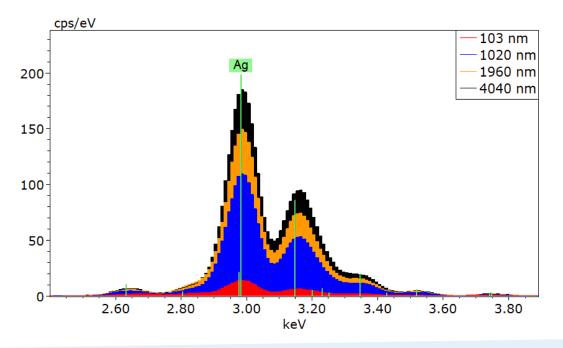


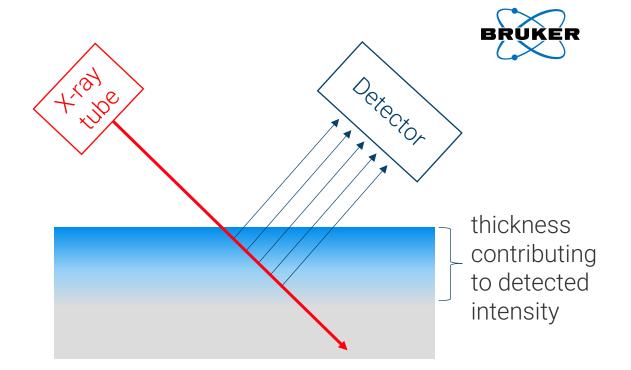
©Innovent e.V. – https://www.innovent-jena.de/mos/yig



### Intro Thickness analysis using micro-XRF

- X-rays can penetrate deeply into many materials.
- $\rightarrow$  Characteristic X-rays can be generated in varying sample depths.



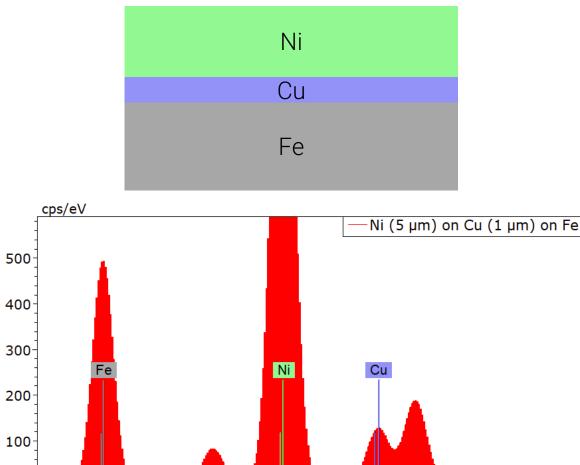


- X-rays from high depths will be absorbed before reaching the surface.
- $\rightarrow$  Detected intensities will increase with sample thickness up to a maximum.
- $\rightarrow$  Intensities of characteristic X-rays may be used to deduce layer thicknesses.

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#### Intro **Thickness analysis using micro-XRF**

- Interlayer effects are often important.
- Layer stacking needs to be known.
- Quantification may be done purely based on reference-materials or in a fundamental parameter based approach that may, but must not necessarily be calibrated using reference materials.



7.5

keV

8.0

6.5

7.0



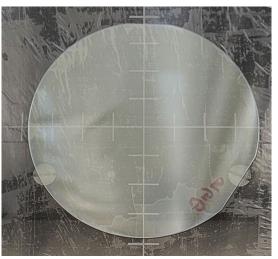
8.5

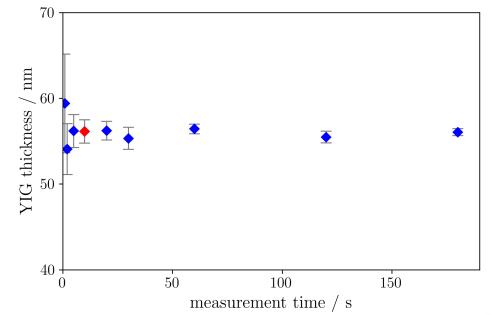
9.0

#### Quality control YIG layer analysis – Measurement time I

- The objective of quality control might be to map variations in thickness of YIG on the sample surface.
- $\rightarrow$  Mappings or point analyses on a grid may be performed.
- Measurement time is a primary consideration. It is dictated by the required precision.
- For ~ 50 nm of YIG on GGG, measurements should likely not be less than 10 s (red marking) and anything above 60 s will not improve the results.







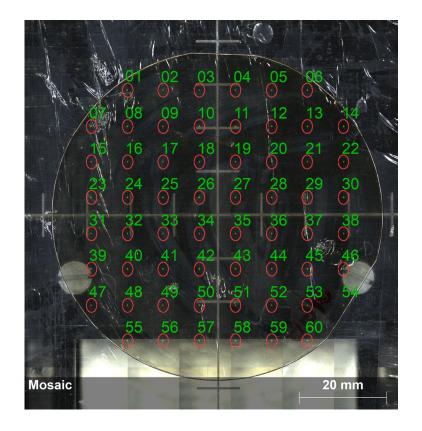
### Quality control YIG layer analysis – Measurement time II

- Given the required measurement times, doing point analyses rather than a mapping is more feasible.
- Decisions must be made regarding the number of points and time per point and will depend on what is required for the user.

Three options were explored:

- 1. 60 measurements on a grid with 60 s per spot (shown on right).
- 2. 60 measurements on a grid with 30 s per spot if lower precision is acceptable.
- 3. 120 measurements on a grid with 60 s per spot if a higher measurement time is acceptable.

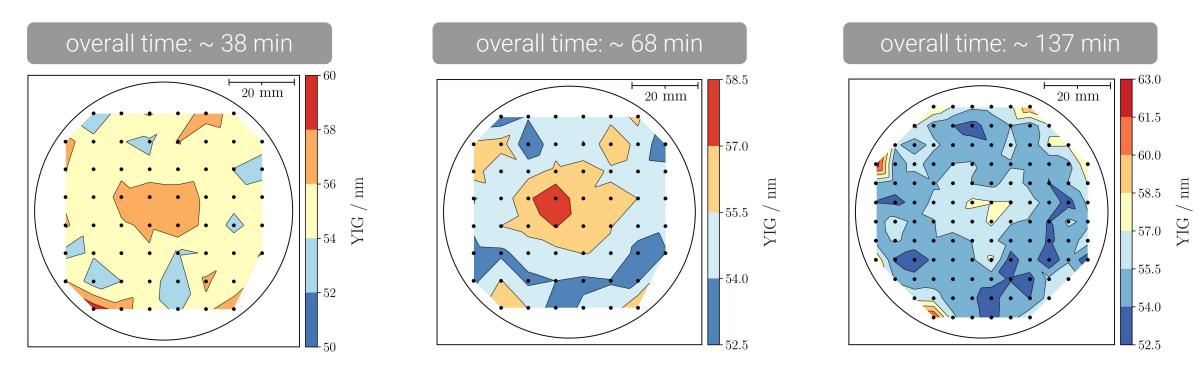




• To ensure that very localized variations are less reflected in the data, a 2000 μm collimator was used.

### Quality control YIG layer analysis – Layer thickness distribution

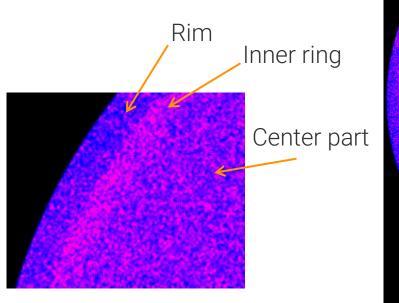




- All measurements show an increased thickness at the center.
- Denser map highlights often-times increasing thickness at the outside.
- Thicknesses were derived without introducing reference materials. YIG thickness according to XRR: 53 nm.

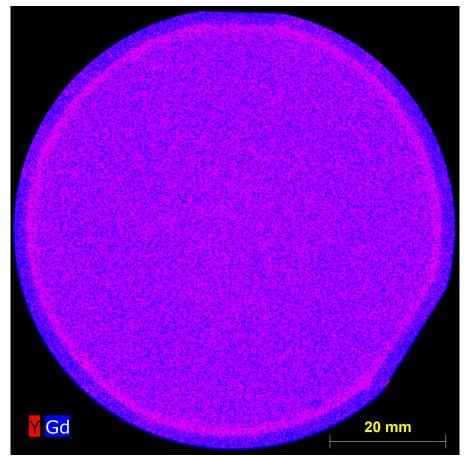
#### Quality control YIG layer analysis – Rim structure

- A map with a polycapillary optic reveals the origin of the anomalies close to the edge.
- There is an outer ring with ~ 2.3 mm width, where very little YIG was deposited, followed by an ~1.7 mm inner ring with increased loading.
- Depending on which part of this ring structure at the edge was hit by the larger Xray spots, either an increased or decreased thickness of YIG was quantified.





#### overall time: ~ 14 h 30 min



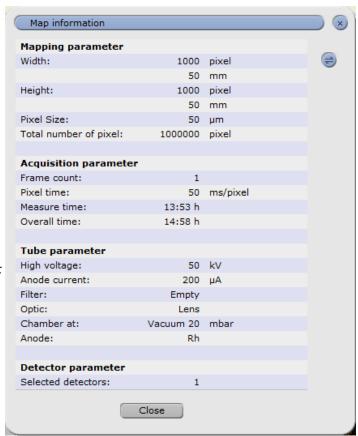
#### **Quality control Components for PEC cells**



Cu:Al gradient layer, manufactured through magnetron sputtering of a dual Cu/Al target by K. Harbauer, W. Kohrt, K. Ellmer, Helmholtz-Zentrum Berlin für Materialien und Energie

Photoelectrochemical (PEC) cells can produce hydrogen from water when exposed to sunlight.

 The efficiency of the process, as well as the stress due to corrosion depend strongly on a finely tuned set of technical parameters – layer thickness and composition is one of them.

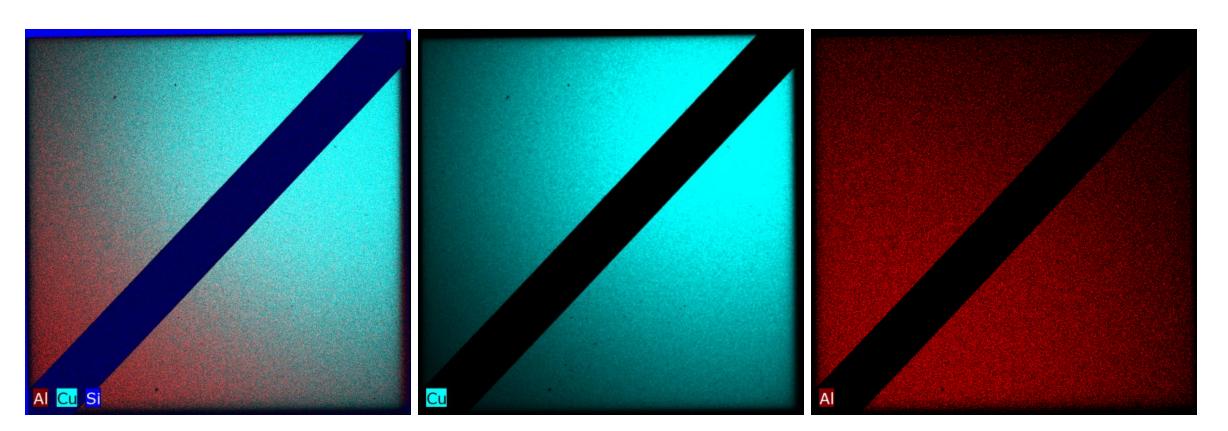




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#### Quality control Components for PEC cells – Qualitative analysis

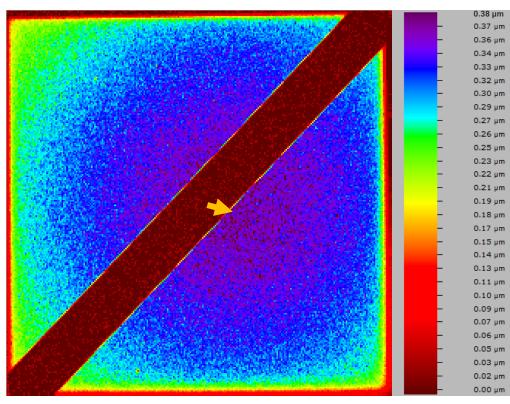


• Cu/Al-layer on a glass substrate: the concentration gradient is clearly visible





#### Quality control Components for PEC cells – Layer thickness quantification



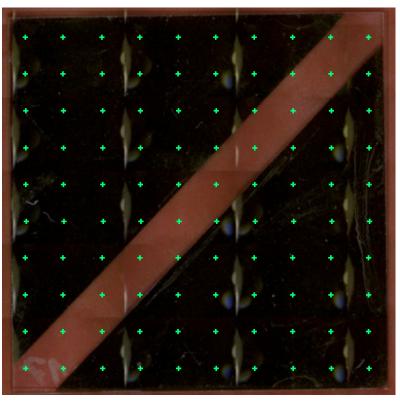
- Knowing the structure of the sample, a method for layer thickness analysis can be set up quickly.
- A full quantification of the map data (here with 5x5 binning) shows the layer thickness distribution with high spatial resolution (250 µm per pixel).
- ... but it also takes time.
- The radially symmetric distribution pattern is visibly offset from the center.
- Structure
  Layer
  Chemical elements
  layer1
  Cu
  Al
  base
  Si
  Measure conditions
  Parameter
  Value
- ParameterValueHV / kV50Current / μA200Collimator25 μm LENSAtmosphereVacuum

Note: for sample systems like this there are no certified reference materials.
 → the quantification is based on fundamental parameters and known physics (and can be supported by samples of trusted composition).





#### Quality control Components for PEC cells – Quantitative point analysis



• 10x10 grid.

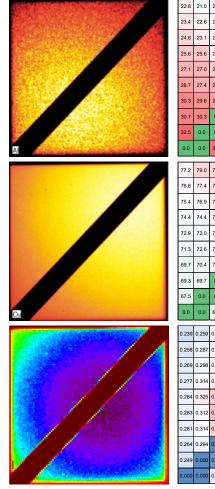
- When the expected variations are on a millimeter-scale, there is no need to measure with micrometer resolution.
- To save measurement time, an array of points can be set and measured.
- Point spectra can be quantified using the same layer analysis method.
- The results (layer thicknesses and composition) are shown in tabular from and can be exported to text files.
- This allows, for example, to visualize the result of the element and layer thickness distribution.

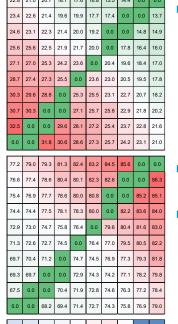


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• Measurement time per point is 10 s.

#### **Quality control Components for PEC cells – Comparison of results**

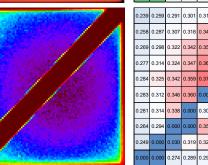




Element distribution of AI (qualitative, left) shows maximum is not in the corner, the layer composition (quantitative, right) shows that the highest Al:Cu ratio (33:67) is in the bottom-left corner.

Element distribution of Cu (qualitative, left)

The layer composition (quantitative, right) shows the highest Cu:Al ratio (86:14) in the top-right corner.



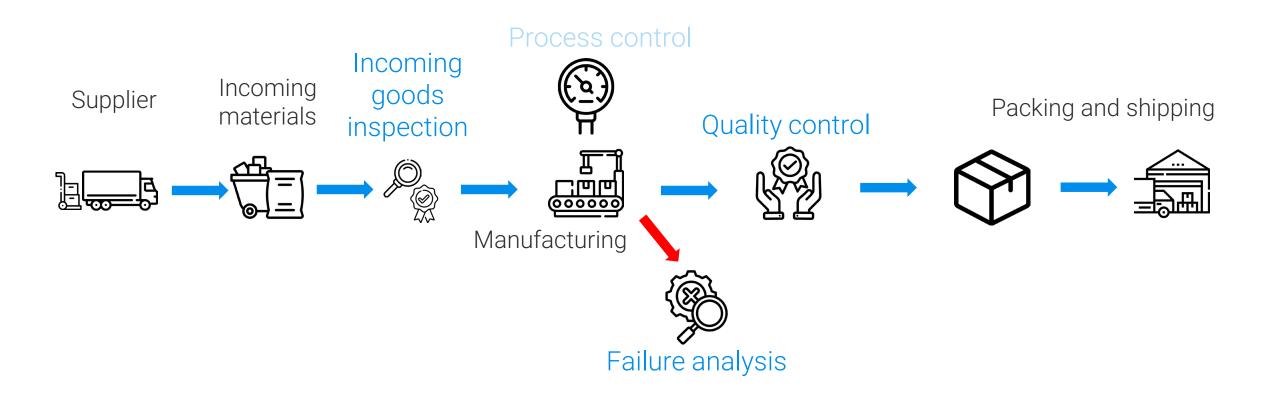
Very similar results with respect to position and min/max-values of the layer thickness distribution.

Spatial resolution vs. measurement time (here 250  $\mu$ m with 15 h vs. 5 mm with < 20 min)





#### **Summary**

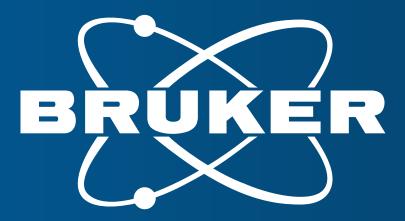




# Thank you!

Are there any questions?

For more information, please contact us: info.bna@bruker.com



Innovation with Integrity